

UM-DIPA SLG46625-APDIPA SLG46625-AP Rev.1.00

User manual

UM-DIPA SLG46625-AP

DIP Adapter SLG46625-AP

Abstract

This document describes the DIP Adapter SLG46625-AP functionality and provides a quick start guide.

Contents

Abstract	1
1. Terms and Definitions	3
2. References.....	3
3. Introduction and board overview	4
4. Design emulation, programming and real time testing	5
5. Board dimensions	5
6. Schematic diagrams	6
7. Bill of materials	7
8. Revision History	8

Figures

Figure 1. DIPA views	4
Figure 2. Light Development Board with DIPA.....	5
Figure 3. Board assembly top view dimensions	5
Figure 4. Board assembly side view dimensions.....	5

Tables

Table 1. DIPA pinout description	4
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1. Terms and Definitions

DIPA	DIP Adapter SLG46625-AP
GPI	General Purpose Input
GPIO	General Purpose Input/Output
IC	Integrated Circuit
SA	Socket Adapter
TP	Test point

2. References

[1] [SLG46625-A Datasheet](#)

3. Introduction and board overview

DIPA is a compact, easy to use hardware tool that provides SLG46625-AP^[1] IC hardware support for design emulation, programming and real time testing. DIPA is controlled by Go Configure Hub software with emulation and IC programming.

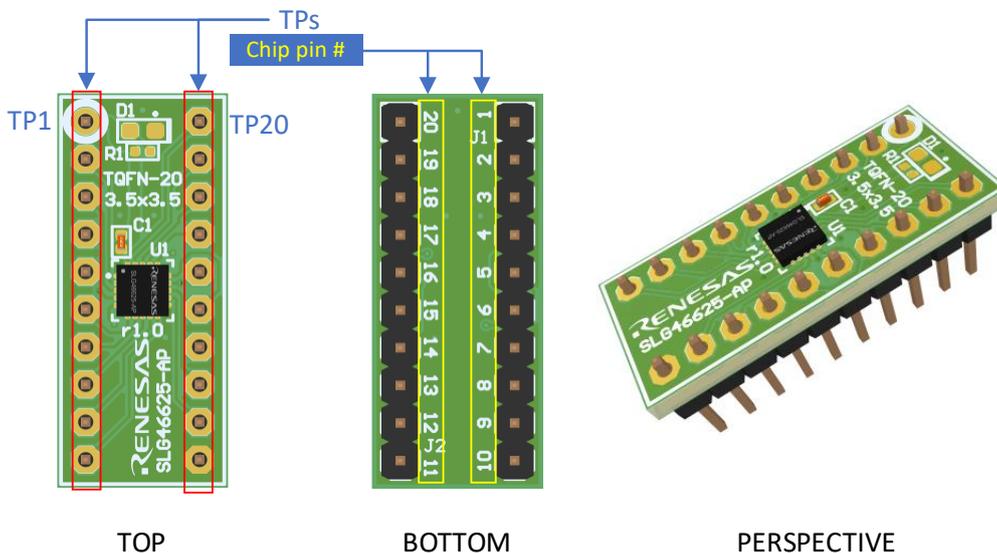


Figure 1. DIPA views

Table 1. DIPA pinout description

Chip pin #	SA connector J1 pin #	Pin Functions
1	TP1	Power Supply
2	TP2	GPI, External Reset ADC CLK
3	TP3	GPIO with OE, ACMP4(+)
4	TP4	GPIO, ACMP5(+)
5	TP5	GPIO with OE, ACMP5 (-)
6	TP6	GPIO, ACMP0(+)/ACMP1(+)/ACMP2(+)/ACMP3(+)/ACMP4(+)
7	TP7	GPIO with OE, ACMP0(-)/ACMP1(-)/PGA_OUT
8	TP8	GPIO, POR Output, PGA(+)
9	TP9	GPIO with OE,PGA(-)
10	TP10	GPIO with OE, ACMP0(-)/ACMP1(-)/ACMP2(-)/ACMP3(-)/ACMP4(-), Super Drive IO
11	TP11	Ground
12	TP12	GPIO, ACMP1(+), Super Drive IO
13	TP13	GPIO with OE, ACMP2(+)/ACMP3(+)
14	TP14	GPIO with OE, ACMP2(-)
15	TP15	GPIO ,ACMP3(+)/ACMP4(+)
16	TP16	GPIO with OE, AIN MUX/CNT
17	TP17	GPIO
18	TP18	GPIO with OE, Vref OUT 1
19	TP19	GPIO with OE, Vref OUT 0
20	TP20	GPIO General Purpose IO

4. Design emulation, programming and real time testing

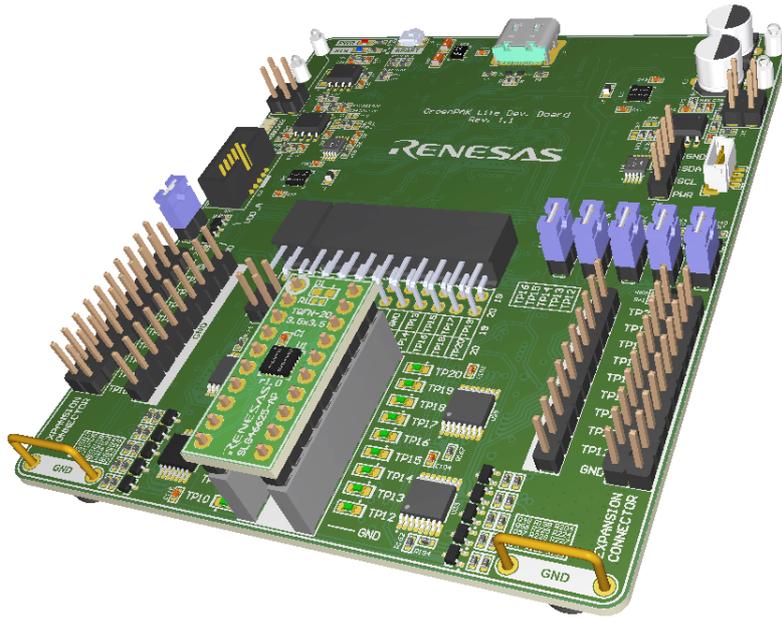


Figure 2. Light Development Board with DIPA

5. Board dimensions

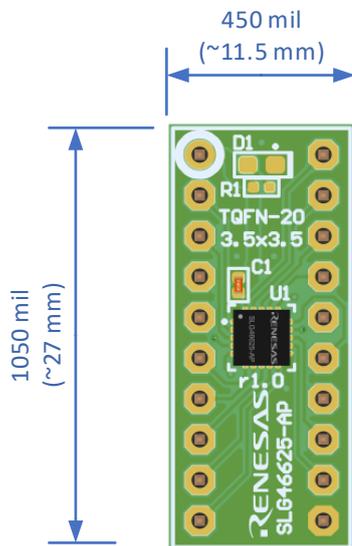


Figure 3. Board assembly top view dimensions

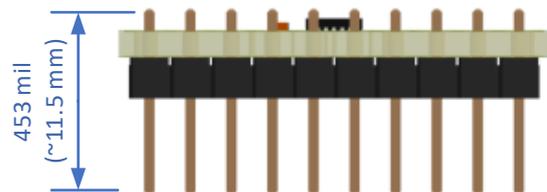
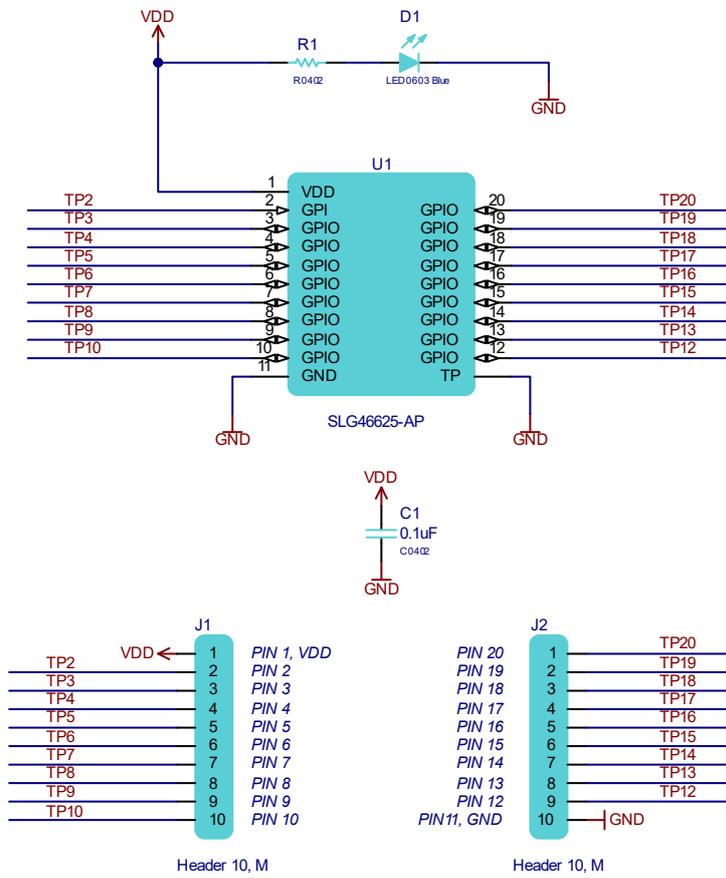


Figure 4. Board assembly side view dimensions

6. Schematic diagrams



Note: D1, R1 are optional (not mounted by default). May be used for power presence indication.

7. Bill of materials

#	Designator	Manufacturer Part Number	Manufacturer 1	Quantity
1	C1	C1005X7R1H104K050BB	TDK	1
2	J1, J2	PH1-10-UA	Adam Equipment	2
3	U1	SLG46625-AP	Renesas Electronics America	1
	Optional			
1	D1	SMD LED 0603	-	1
2	R1	SMD RES 0402 1k	-	1

8. Revision History

Revision	Date	Description
1.00	Sep 02, 2025	Initial release.

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